



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

April 20, 2009

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING METHOD

Serial No.: 10/576 230

Group: 1792

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Examiner: Bareford

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Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

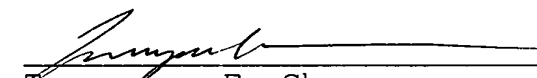
LETTER TRANSMITTING APPEAL BRIEF FEE

Sir:

Enclosed is Appellants' check in the sum of \$540.00, representing payment of the Appeal Brief fee. The Commissioner is hereby authorized to charge any additional fee which may be required by this paper, or to credit any overpayment, to Deposit Account No. 06-1382.

Respectfully submitted,

TFC/smd


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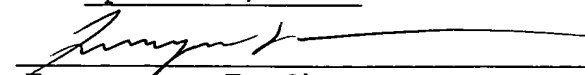
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Encl: Check (\$540)
Appellants' Brief on Appeal
Claims Appendix
Evidence Appendix
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on April 20, 2009.


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